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Molding Compounds for Power Device Market, Global Outlook and Forecast 2022-2028

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Abstracts

At present, the most widely used packaging material is plastic packaging, and more than 95% of electronic devices use plastic packaging.

This report contains market size and forecasts of Molding Compounds for Power Device in global, including the following market information:

Global Molding Compounds for Power Device Market Revenue, 2017-2022, 2023-2028, ($ millions)

Global Molding Compounds for Power Device Market Sales, 2017-2022, 2023-2028, (Tons)

Global top five Molding Compounds for Power Device companies in 2021 (%)

The global Molding Compounds for Power Device market was valued at million in 2021 and is projected to reach US$ million by 2028, at a CAGR of % during the forecast period 2022-2028.

The U.S. Market is Estimated at $ Million in 2021, While China is Forecast to Reach $ Million by 2028.

Transistors Segment to Reach $ Million by 2028, with a % CAGR in next six years.

The global key manufacturers of Molding Compounds for Power Device include Sumitomo Bakelite, Showa Denko, Chang Chun Group, Hysol Huawei Electronics, Panasonic, Kyocera, KCC, Eternal Materials and Jiangsu zhongpeng new material, etc.

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In 2021, the global top five players have a share approximately % in terms of revenue.

MARKET MONITOR GLOBAL, INC (MMG) has surveyed the Molding Compounds for Power Device manufacturers, suppliers, distributors and industry experts on this industry, involving the sales, revenue, demand, price change, product type, recent development and plan, industry trends, drivers, challenges, obstacles, and potential risks.

Total Market by Segment:

Global Molding Compounds for Power Device Market, by Type, 2017-2022, 2023-2028 ($ Millions) & (Tons)

Global Molding Compounds for Power Device Market Segment Percentages, by Type, 2021 (%)

Transistors

MOSFET

Diodes

Others

Global Molding Compounds for Power Device Market, by Application, 2017-2022, 2023-2028 ($ Millions) & (Tons)

Global Molding Compounds for Power Device Market Segment Percentages, by Application, 2021 (%)

Automotive

Telecommunication

Consumer Electronics

Other

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Global Molding Compounds for Power Device Market, By Region and Country, 2017-2022, 2023-2028 ($ Millions) & (Tons)

Global Molding Compounds for Power Device Market Segment Percentages, By Region and Country, 2021 (%)

- North America
  - US
  - Canada
  - Mexico
- Europe
  - Germany
  - France
  - U.K.
  - Italy
  - Russia
  - Nordic Countries
  - Benelux
  - Rest of Europe
- Asia
  - China
  - Japan

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South Korea

Southeast Asia

India

Rest of Asia

South America

Brazil

Argentina

Rest of South America

Middle East & Africa

Turkey

Israel

Saudi Arabia

UAE

Rest of Middle East & Africa

Competitor Analysis

The report also provides analysis of leading market participants including:

Key companies Molding Compounds for Power Device revenues in global market, 2017-2022 (Estimated), ($ millions)

Key companies Molding Compounds for Power Device revenues share in global market, 2021 (%)

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Key companies Molding Compounds for Power Device sales in global market, 2017-2022 (Estimated), (Tons)

Key companies Molding Compounds for Power Device sales share in global market, 2021 (%)

Further, the report presents profiles of competitors in the market, key players include:

Sumitomo Bakelite

Showa Denko

Chang Chun Group

Hysol Huawei Electronics

Panasonic

Kyocera

KCC

Eternal Materials

Jiangsu zhongpeng new material

Shin-Etsu Chemical

Tianjin Kaihua Insulating Material

HHCK

Scienchem

Beijing Sino-tech Electronic Material

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